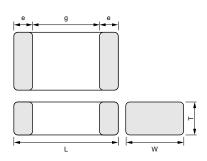
Data Sheet

Monolithic Ceramic Capacitors

GRM0335C1H8R6CD01 (0201, C0G, 8.6pF, 50Vdc)

☐: packaging code

RoHS regulation conformity parts



■ Dimensions

Length L	0.6mm±0.03mm
Width W	0.3mm±0.03mm
Thickness T	0.3mm±0.03mm
Electrode e	0.1 to 0.2mm
Electrode Gap g (min.)	0.2mm

■ Rated Value

	Murata PN Code	Spec
Temperature Char.	5C	COG (EIA), 0±30ppm/°C
Capacitance	8R6	8.6pF
Capacitance Tol.	С	±0.25pF
Rated Voltage	1H	50Vdc

Packaging

Code	Packaging	Minimum Quantity
D	180mm Paper Tape	15000
J	330mm Paper Tape	50000
В	Bulk(Bag)	1000

■ Specifications

PDF file.

Please refer to 'GRM Series Specification and Test Methods (1)'

This data sheet is applied for CHIP MONOLITHIC CERAMIC CAPACITOR used for General Electronics equipment for your design.

- Use of Sn-Zn based solder will deteriorate reliability of MLCC. Please check with our sales representatives for the use of Sn-Zn based solder in advance.
- The RoHS compliance means that we judge from EU Directive 2002/95/EC the products do not contain lead, cadmium, mercury, hexavalent chromium, PBB and PBDE, except exemptions stated in EU Directive 2002/95/EC annex and impurities existing in natural world.
- This statement does not insure the compliance of any of the listed parts with any laws or legal imperatives developed by any EU members individually with regards to the RoHS Directive.

- 1. This datasheet is downloaded from the website of Murata Manufacturing co., Itd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
- 2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.